

Choosing the Right Surface Imaging Technique

With so many surface imaging techniques available, it can be a challenge to select the best method for your project. Each technique provides surface data which can impact numerous functional characteristics of materials, parts, and devices. This guide will provide a quick reference of key considerations to help you make the best choice, faster.

Considerations When Choosing a Surface Imaging Technique

Diverse techniques exist which can directly and indirectly measure surface finish, roughness and critical dimensions of surface features and structures. These vary in their scale of detail and scope, as well as in the types of output information they can provide. Here we break down 8 common surface imaging and profiling techniques through 2 considerations that can identify the best option for you.

Consideration 1: Lateral Resolution vs Vertical Scan Range

For surface roughness and topology analysis, it is important to consider both the scale of the features you want to measure, AND the size of the surface area you need to analyze.

To simplify narrowing your field of surface imaging options, use the guide below to select a technique with a scan range that will span the height / thickness variation in the target area, as well as a lateral resolution adequate to clearly resolve the required features. Then ensure that the technique you choose has a field of view that will cover the area over which you need measurement.





Consideration 2: Technique Specifications & Applications

Consider what output information each technique can provide. Balance the cost required to secure the right data for your project.

| | Contact / Stylus Methods | | Optical Profiling / Microscopy | | | | Electron Microscopy | |
|---|--|--------------------------|--|---|--|---|---|---|
| Technique | Atomic Force Microscopy (AFM) | Stylus Profilometry | Chromatic Dispersion Profilometry (CDP/FRT) | Laser Scanning Confocal Microscopy (LSCM/VK) | White Light Interferometry (WLI) | 3D Patterned Light Measurement | Scanning Electron Microscopy (SEM) | Transmission Electron Microscopy (S/TEM) |
| Prices Start at | \$225 / image | \$225 / hour | \$360 / hour | \$300 / hour | \$225 / hour | \$275 / hour | \$275 / hour | \$850 / sample with prep |
| Field of View (min to max diameter) | 200 nm to 70 μm | N/A | 160 μm to 800 μm | 100 µm to 1 mm * | 5 µm to 200 mm * | 4 mm to 24 mm * | 1 μm to 2 mm | 2 nm to 10 µm |
| Vertical Precision | Å | nm | nm | nm | Å | 3-5 µm | nm | Å |
| Strengths | Very High Resolution (Angstroms) | Large Scan Area | Large Scan Area, High Vertical Res. | Balanced Vertical / Lateral Res. | High Vertical Resolution | Macroscopic Dimensional Measurement | High-Res in situ Nano- manipulator | Best Resolution (Atomic Scale) |
| Max Sample Diameter | 300 mm if centered | 200 mm in- house | 200 mm in- house | Flexible | Flexible | Flexible | 200 mm | Appx 100 µm (Requires Sample Prep) |
| Works Best on | Smooth, Hard Surfaces | Smooth, Hard Surfaces | Opaque Material, No Steep Slopes | No Steep Slopes | Opaque Material | Opaque Material, No Steep Slopes | Conductive Samples | Nano-scale Features / Defects |
| | Applications | | | | | | | |
| Non-Destructive | | | | • | ٠ | | | |
| Cross Sectional Imaging | • | | • | • | | • | • | • |
| Flexible-Angle Imaging | | | | ٠ | | | • | |
| 1D Height Line-Scan | • | • | • | • | • | • | | |
| 2D Height Map | • | | • | • | | | | |
| 3D Profile | • | | • | • | | | | |
| 3D CAD Model (.stp, .stl) | | | | | | • | | |
| Quantitative Dimensions | • | O | | • | | | • | • |
| Integrated Element Analysis | | | | | | | • | • |
| Nanomechanical Properties | • | | | | | | | |
| | * | | | | , | | | |

* Technique uses single field of view, but images can be stitched together to cover a larger area

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